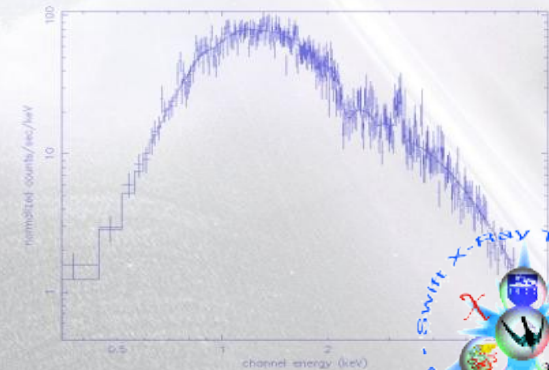
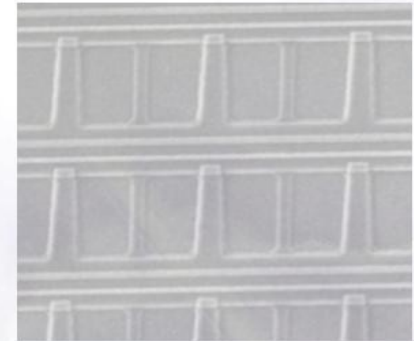
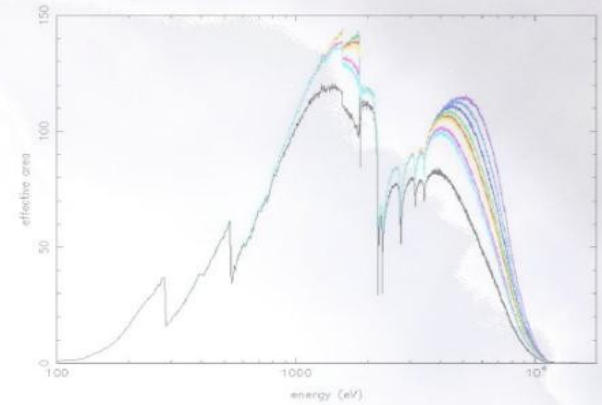


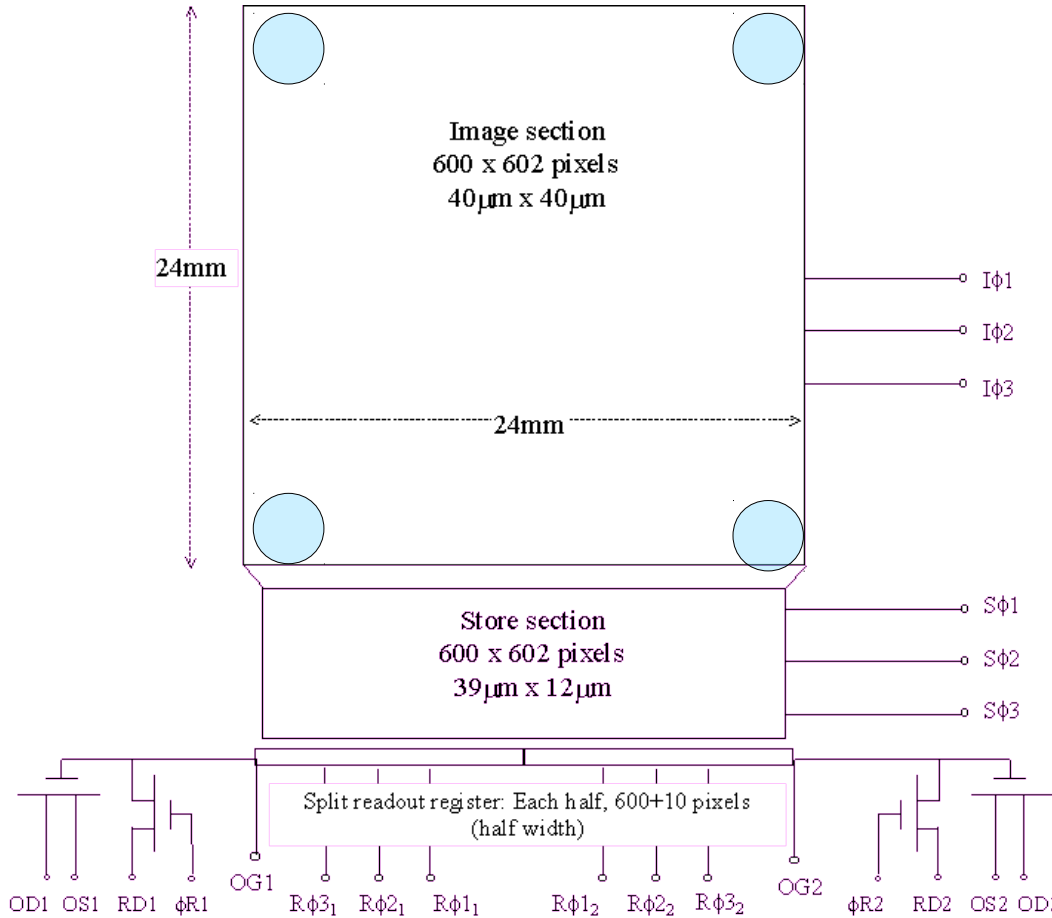
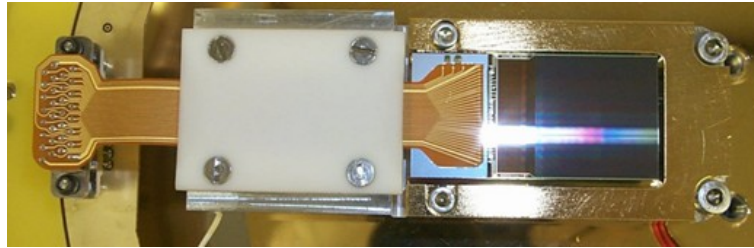
Swift-XRT Calibration Update

Andy Beardmore
and the
Swift-XRT calibration team



- Swift has now been operating for 8+ years
- Makes 35000 slews per year (>99% within 3' accuracy; ~40 targets per day)
- Approaching 750th Swift detected GRB
- Observing time: <20% GRBs, 35% GI/fill-ins, 30% TOOs (>850 per year), 2% Cal
 - Cal: 300 ks every 6 months; 150 ks on Tycho for trap mapping
- XRT CCD temperature range: -70C to -52C (97% of time below -54C, mean of -60C)

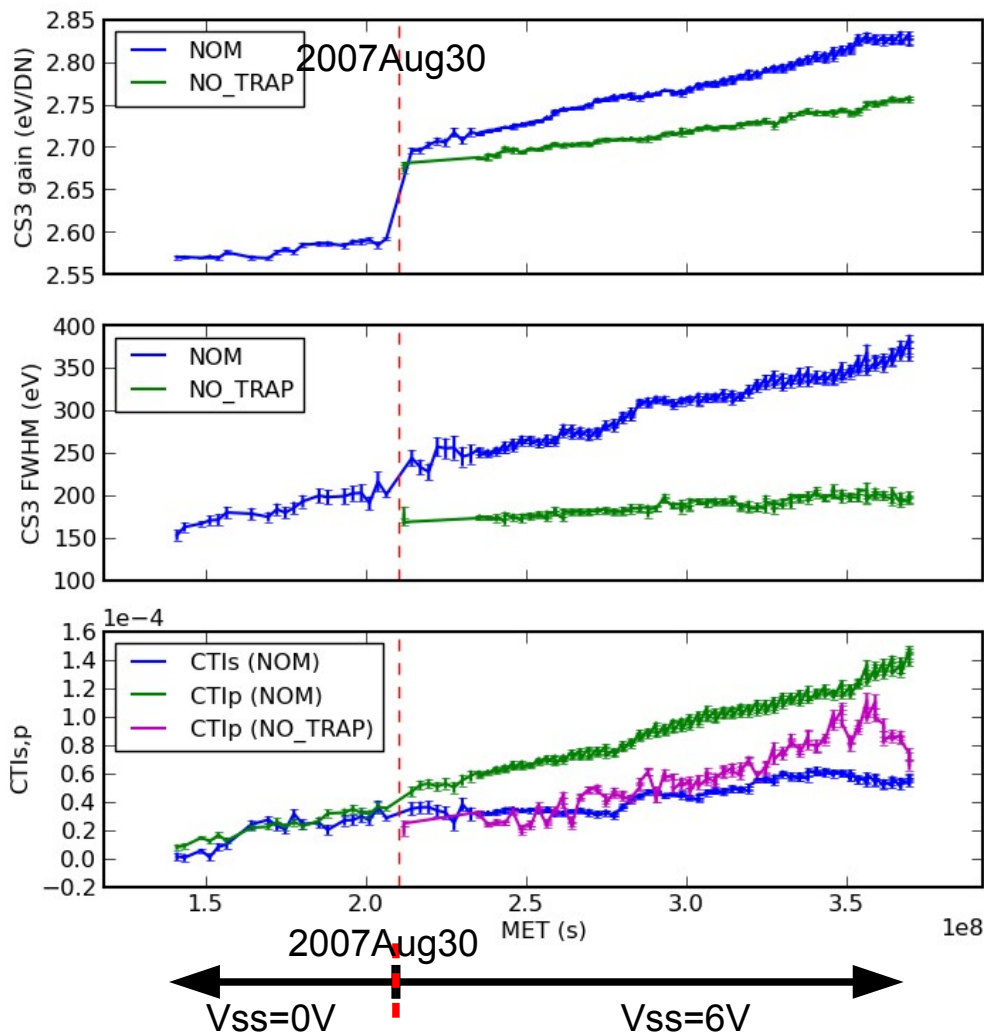




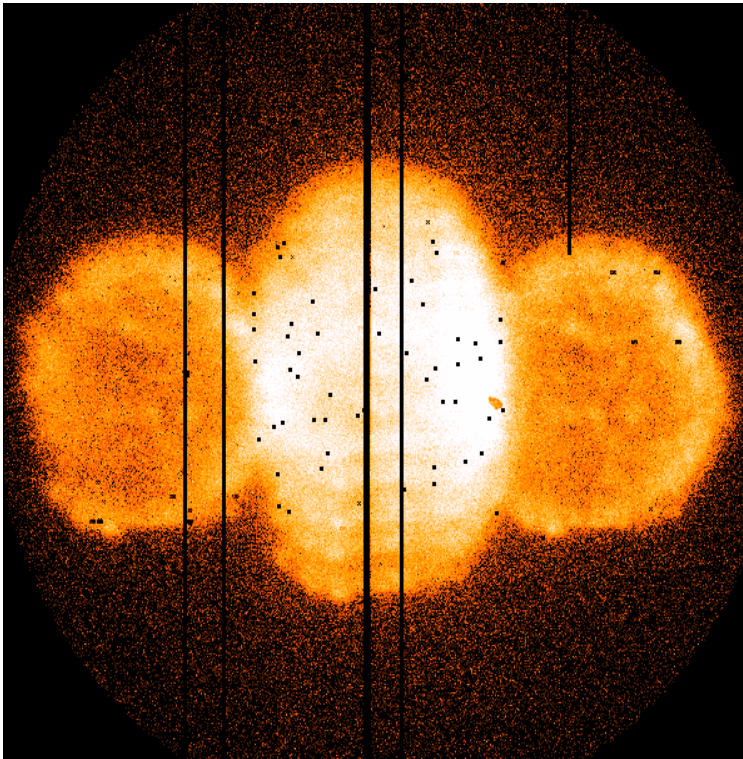
- e2v CCD-22 detector (developed for EPIC MOS camera on XMM-Newton)
- Operated in Photon Counting (PC; $\Delta t=2.5s$) and Windowed Timing (WT; $\Delta t=1.77ms$) mode
- 4 ^{55}Fe corner sources continuously illuminate CCD corners, used to monitor CCD performance
- Spectral resolution at launch: FWHM = 145 eV at Mn K- α (5.895 keV)
- *Swift* in Low-Earth orbit and exposed to high flux of protons during SAA



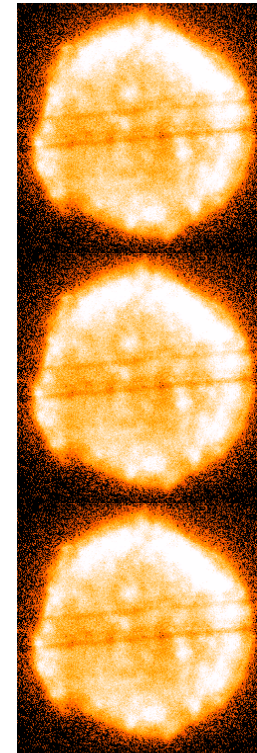
- Gain/CTI measured from corner sources (-60C)



- Tycho SNR observed ~ 6 monthly
- Si-K α used to map the location and depth of the deepest traps (PC), column offsets (WT)



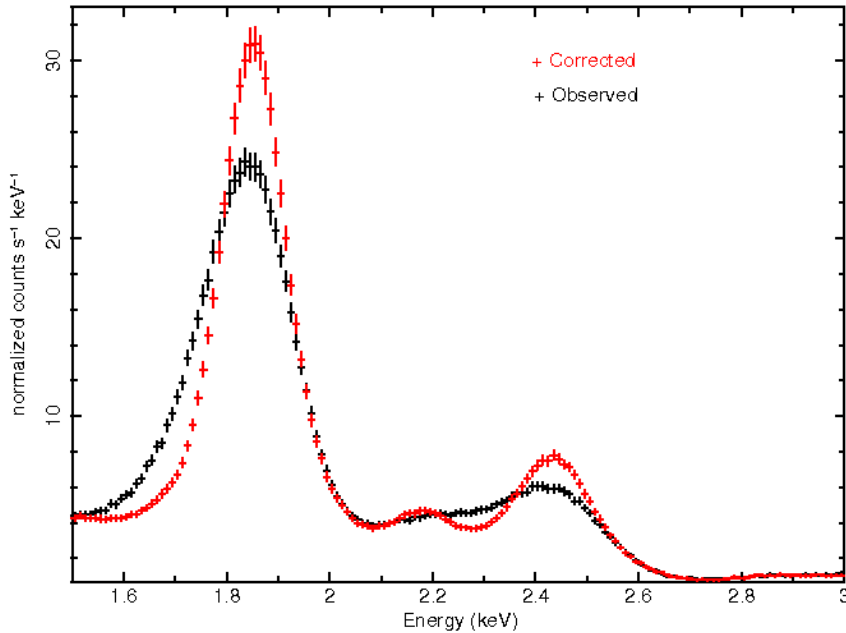
- PC: 7x15ks



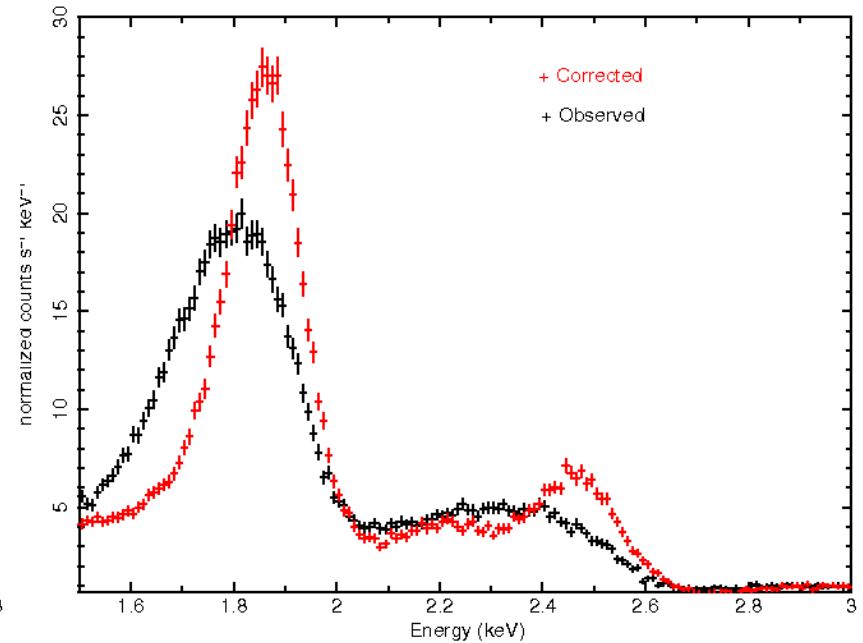
- WT: 3x15 ks



Tycho 2012 PC observations

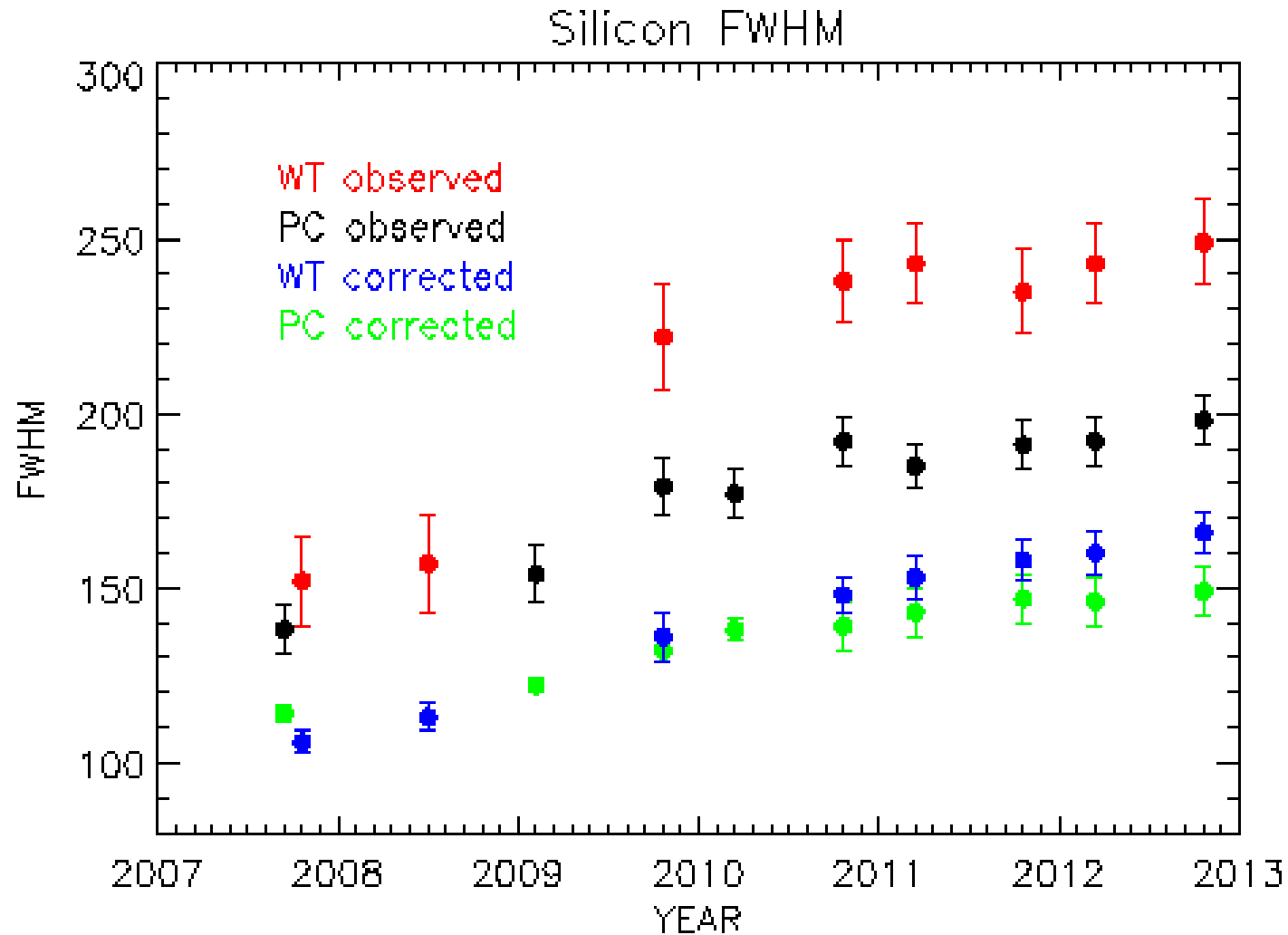


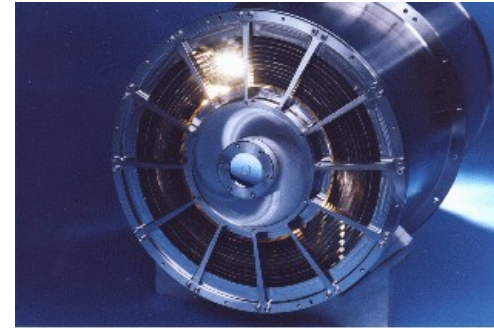
Tycho 2012 WT observations



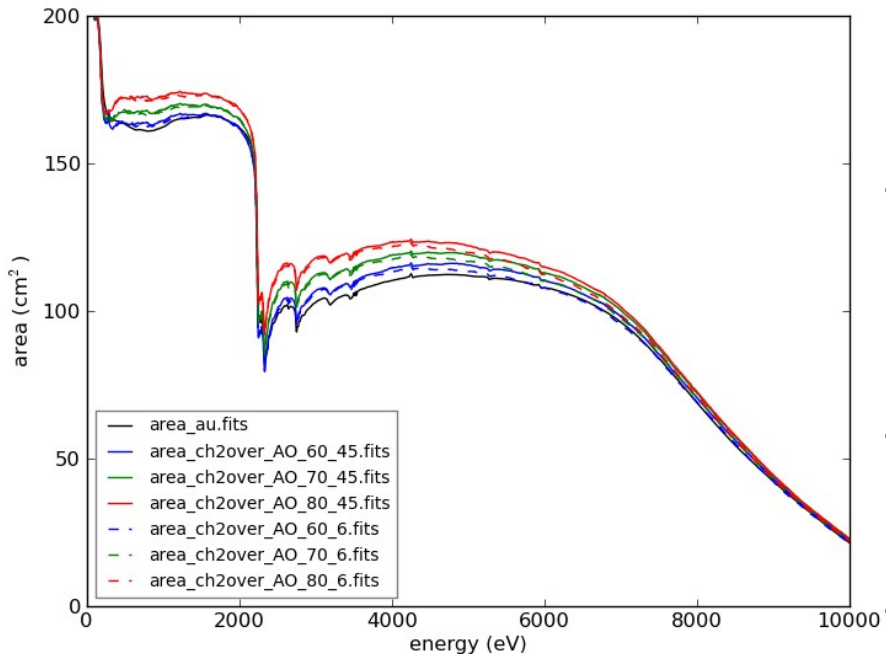
- Energy dependent trap offsets for both PC & WT (modelled as broken powerlaw)
- Temperature dependent trap depths for PC (as thermal noise fills traps when CCD is warmer)







Jet-X flight
Spare mirror
module



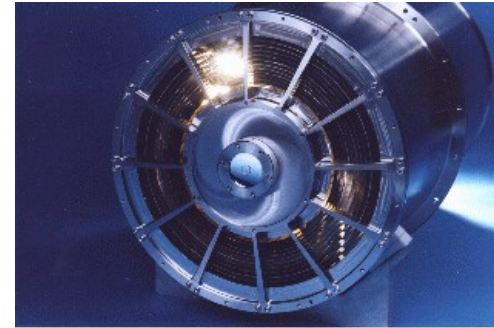
Micro-roughness (rms):

solid = 4.5 Å

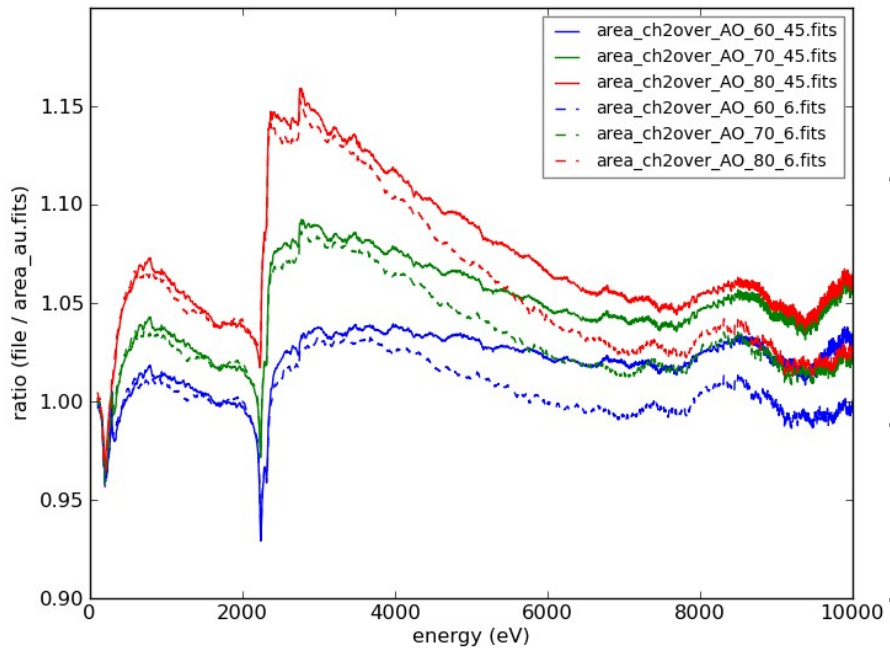
Dashed = 6.0 Å

- New mirror area calculations, including a hydrocarbon (CH₂) overcoat
- Reflectivity increases with thickness of CH₂ layer
- High energy (> 4keV) area turns over faster as the microroughness increases





Jet-X flight
Spare mirror
module

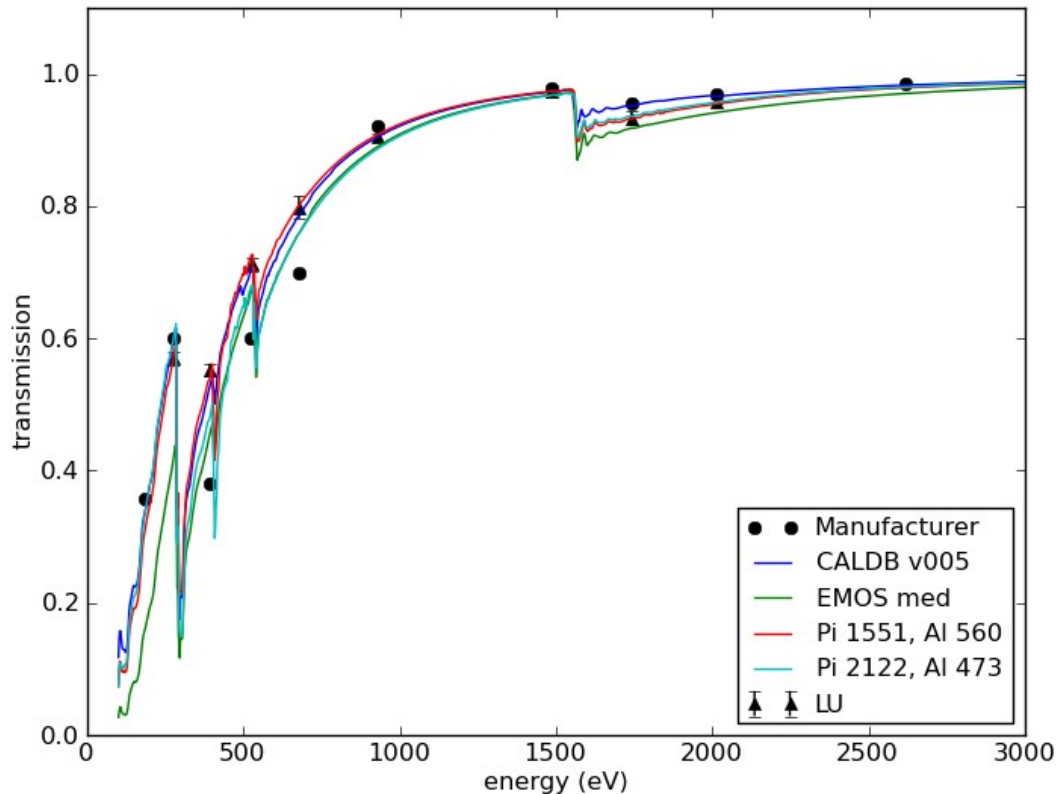


Micro-roughness (rms):
 solid = 4.5 Å
 Dashed = 6.0 Å

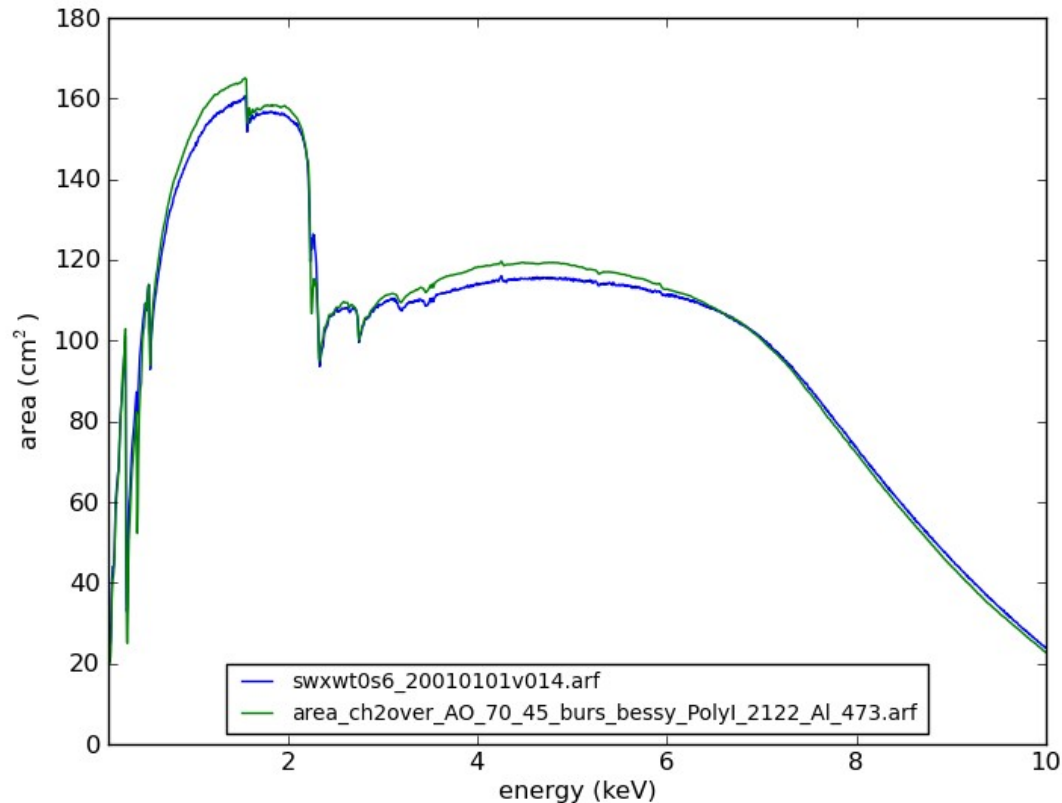
- New mirror area calculations, including a hydrocarbon (CH₂) overcoat
- Reflectivity increases with thickness of CH₂ layer
- High energy (> 4keV) area turns over faster as the microroughness increases



- Fit to LU and manufacturer filter data using new polyimide and aluminium mass absorption coefficients (from M. Barbera, Palermo)



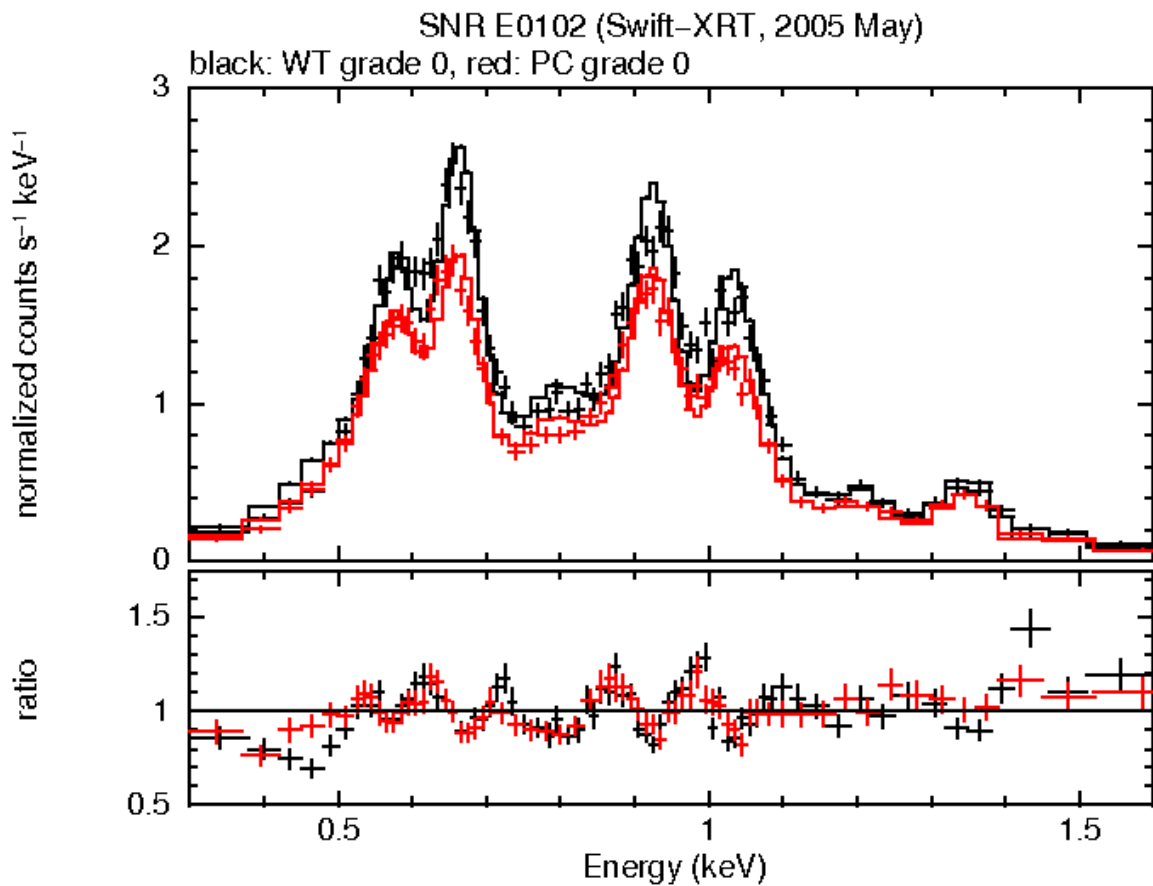
- ARF comparison – CALDB (v014) and new preferred mirror area * filter transmission



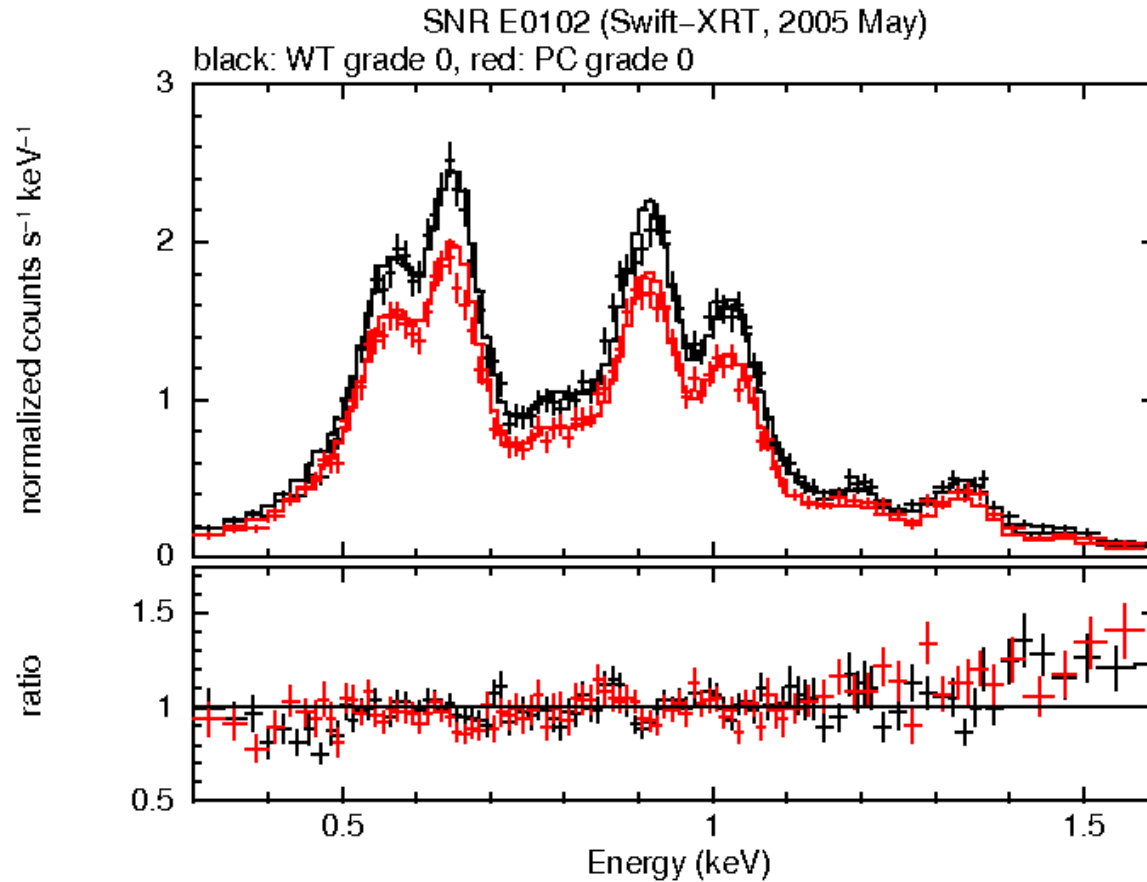
- CCD22 simulator code described last IACHEC
- Use to generate PC and WT mode RMFs
 - PC : 2D, full-frame readout ($\Delta t=2.5s$)
 - WT : 1D readout ($\Delta t=1.77ms$) \rightarrow 10 rows at a time clocked into serial register
- Matched the line broadening to data (2005 & 2007) by increasing the electron noise and CTI
 - EN = $6.75 e^-$ (2005), $8.75 e^-$ (2007 $V_{ss} = 0V$) and $7.5 e^-$ (2007 $V_{ss}=6V$)
 - CTIs,_p = $4e^{-6}$, $8e^{-6}$ (2005); $3.5e^{-6}$ (2007, both $V_{ss}=0V$ and $6V$)



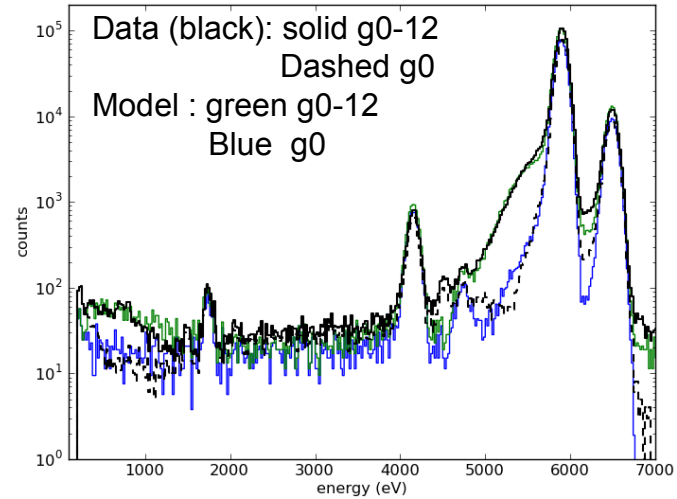
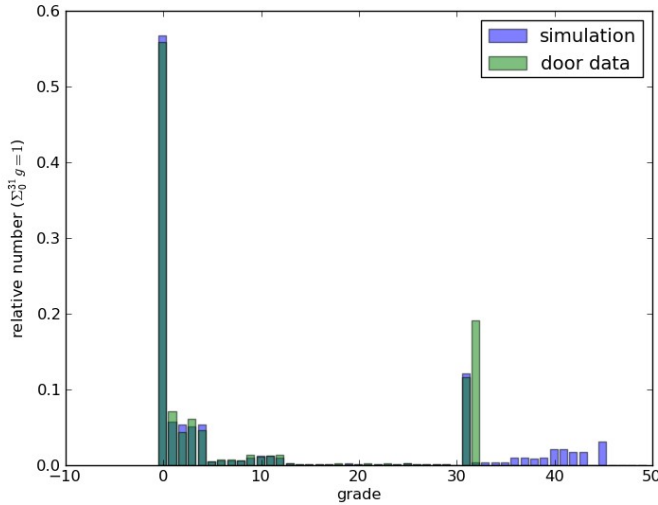
- V011 RMF



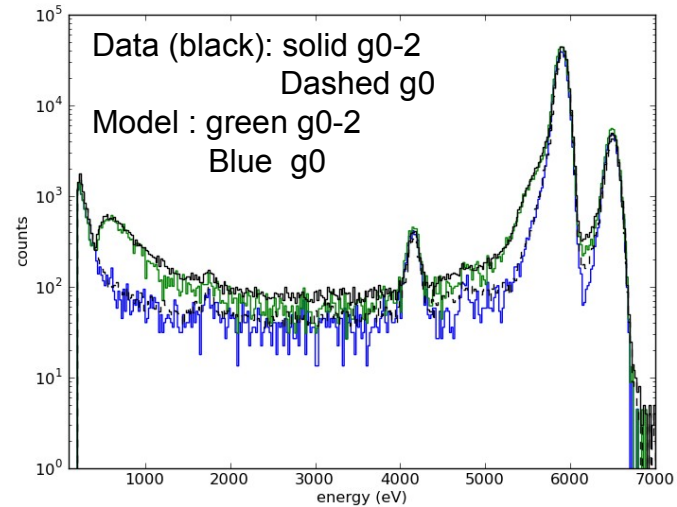
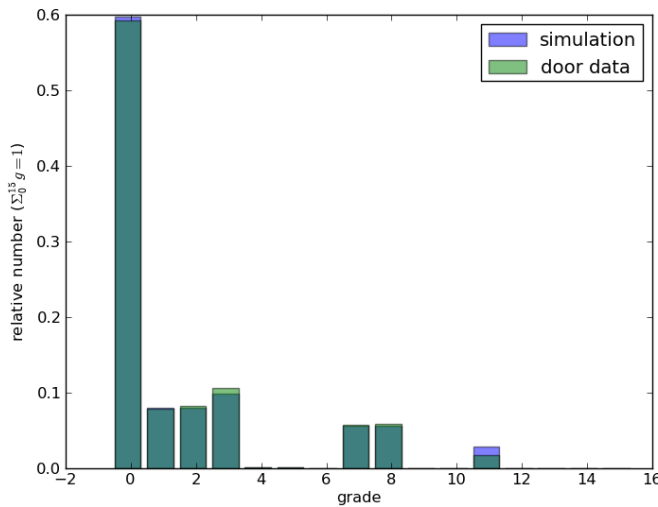
- New 2005 $V_{ss}=0V$ RMF



- Improved LEO door source data modelling ($V_{ss}=0V$)

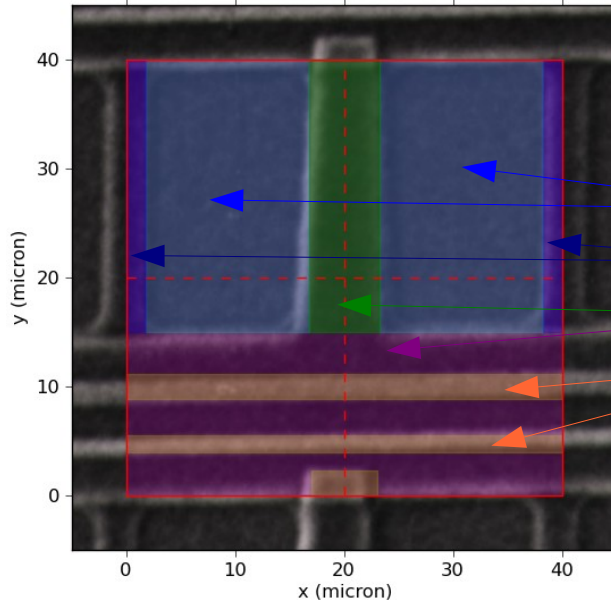


PC



WT





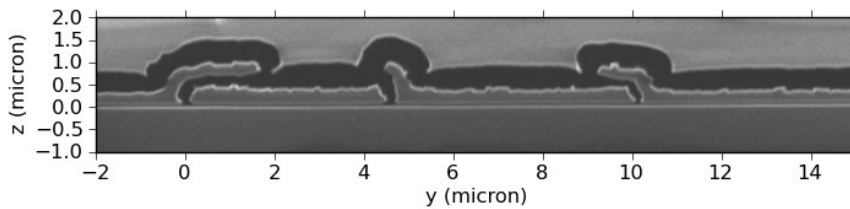
Original Electrode Structure

$$T_1 = \exp(-0.1 \mu_{\text{SiO}_2})$$

$$T_2 = T_1 \exp(-0.1 \mu_{\text{Si}_3\text{N}_4}) \exp(-0.4 \mu_{\text{SiO}_2})$$

$$T_3 = T_2 \exp(-0.25 \mu_{\text{Si}}) \exp(-0.3 \mu_{\text{SiO}_2})$$

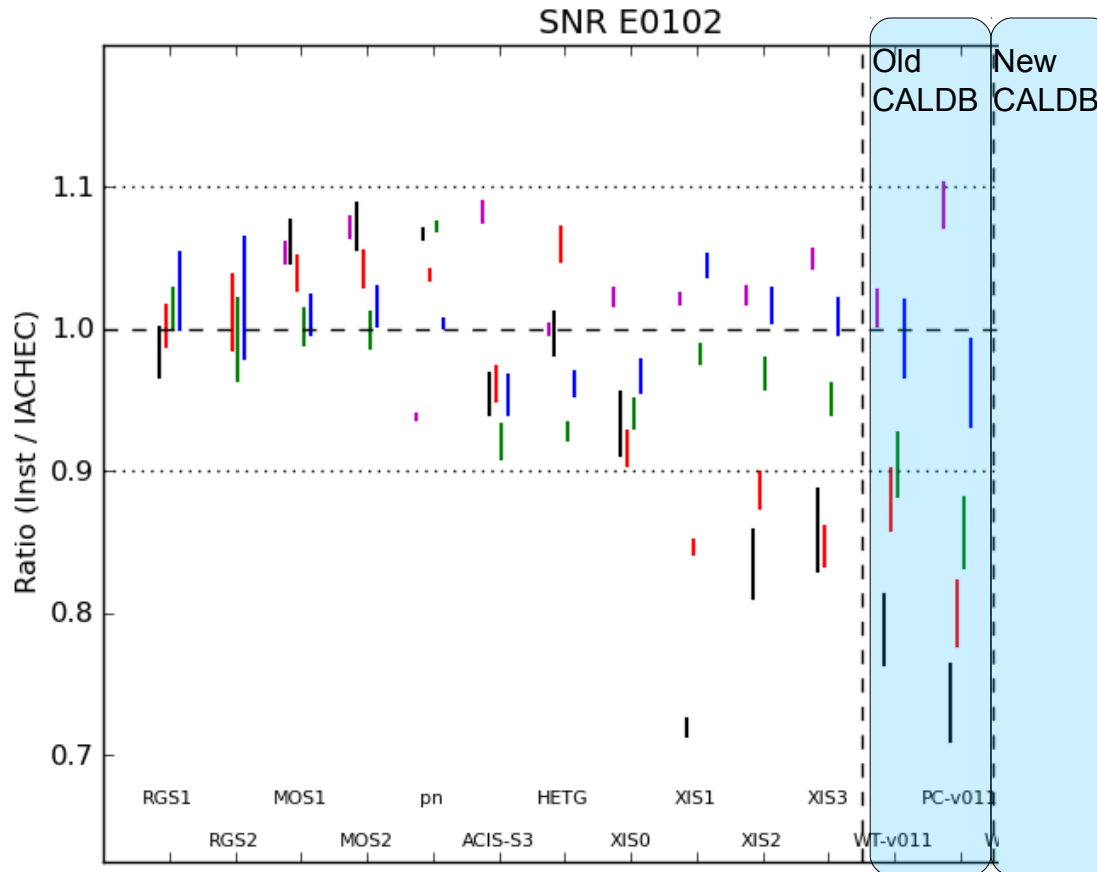
$$T_4 = T_3 \exp(-0.25 \mu_{\text{Si}}) \exp(-0.4 \mu_{\text{SiO}_2})$$



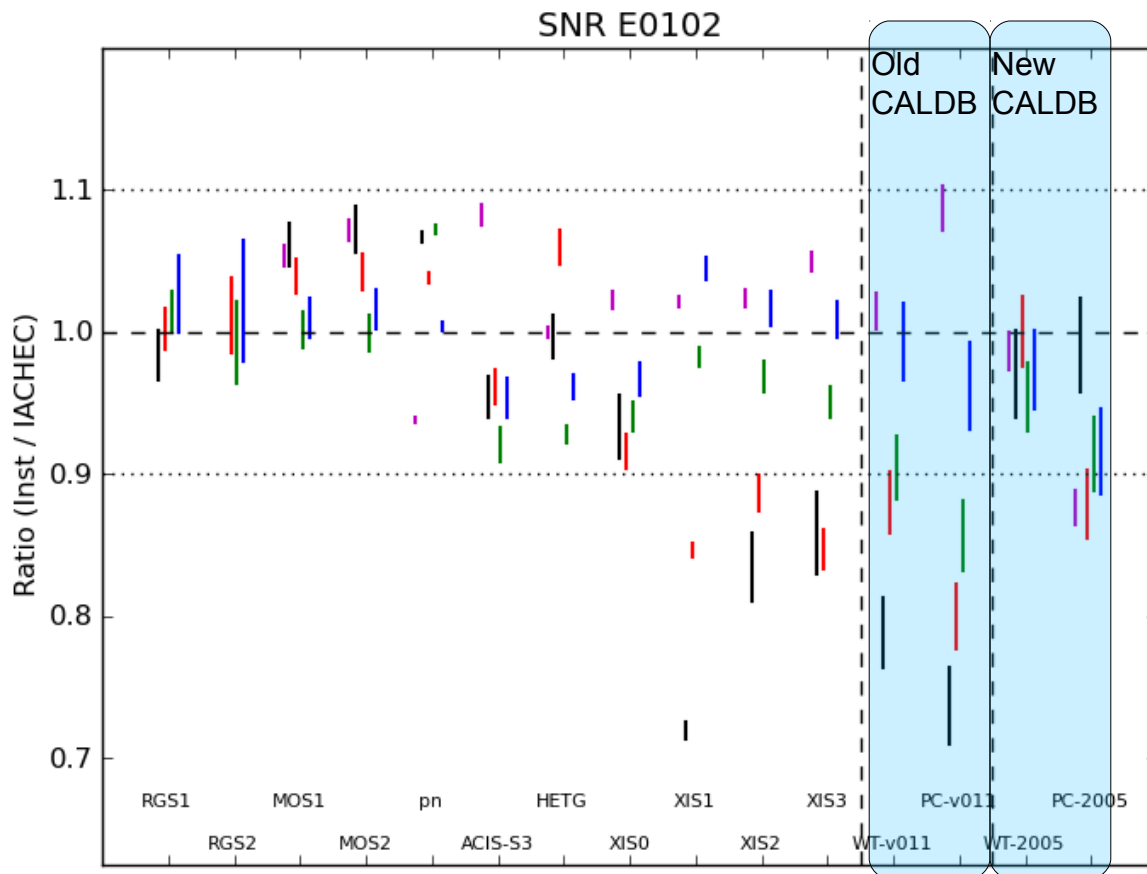
Are the SiO₂ and Si layers thick enough ?

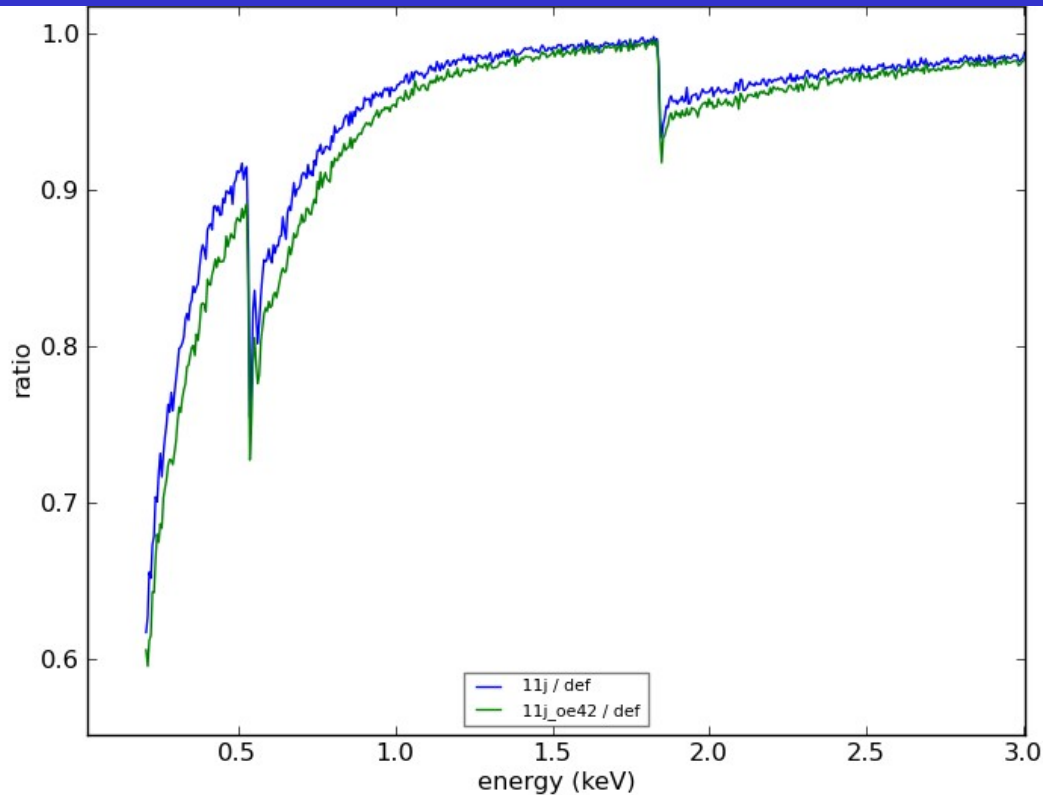


- E0102 WT data from 2005 used to refine the electrode transmission model



- E0102 WT data from 2005 used to refine the electrode transmission model

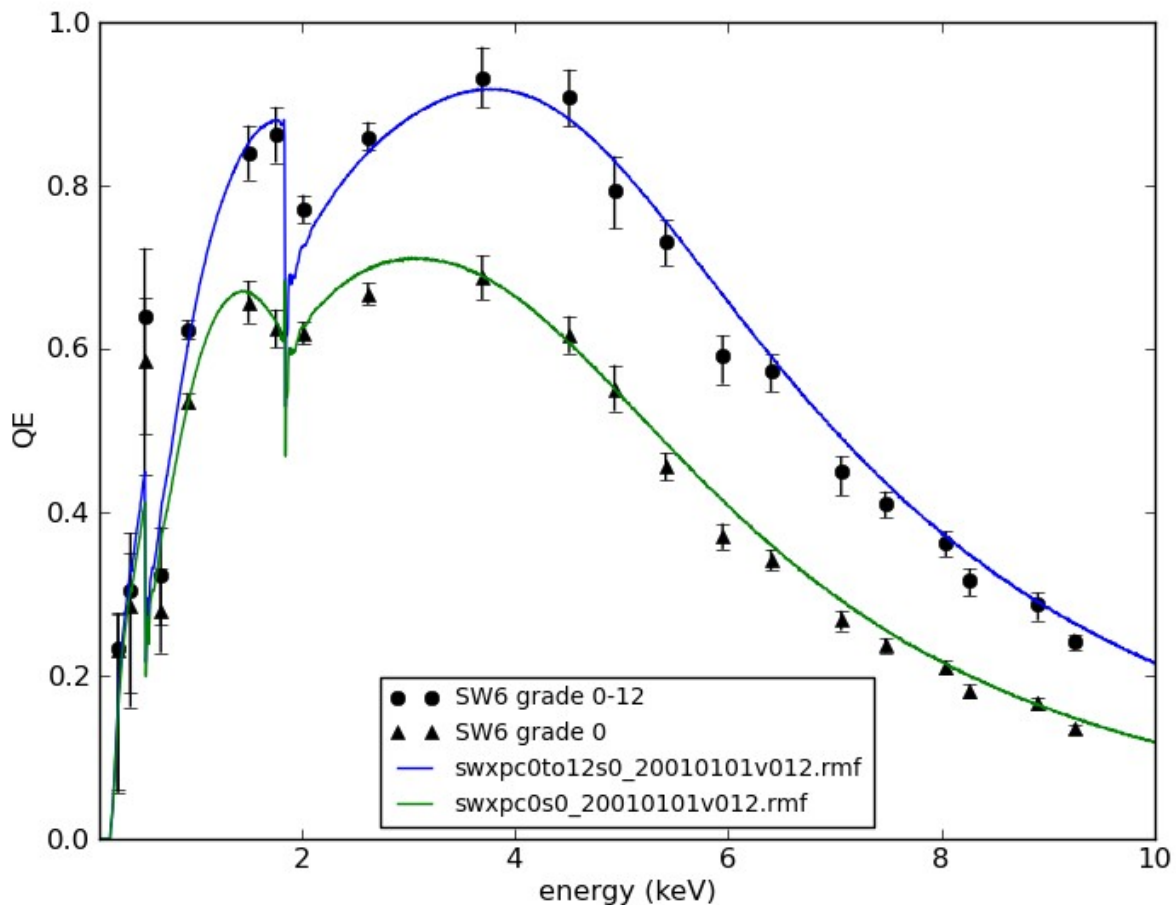




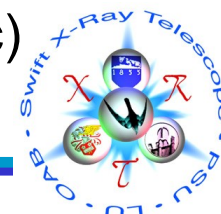
- Blue - QE ratio new electrode / original electrode
 - Base SiO₂ layer : 0.1 → 0.15 micron
 - Si layers : 0.25 → 0.35 micron
- Green - QE ratio new (OE area -5%) / original



- Comparison with (Astrosat) CCD Lab QE



- 2 RMFs * 3 mirror area files * 3 filter files
- Tested on
 - RXJ1856 (WT, PC)
 - Clusters (PC, 90-150 arcs)
 - Abell 1795 (Gal NH=0.012e22 cm²)
 - Abell 2029 (Gal NH=0.033)
 - PKS0745-19 (Gal NH=0.42)
 - H1426 (Gal. NH=0.012) (PC, XMM 2005-Jun)
 - SNRG21.5 (NH=3.1) (PC)
 - 3c273 (Gal. NH=0.017) (WT, XMM 2005-Jul)
 - Mkn421 (Gal. NH=0.019) (WT, MOS1T 2006-Dec)

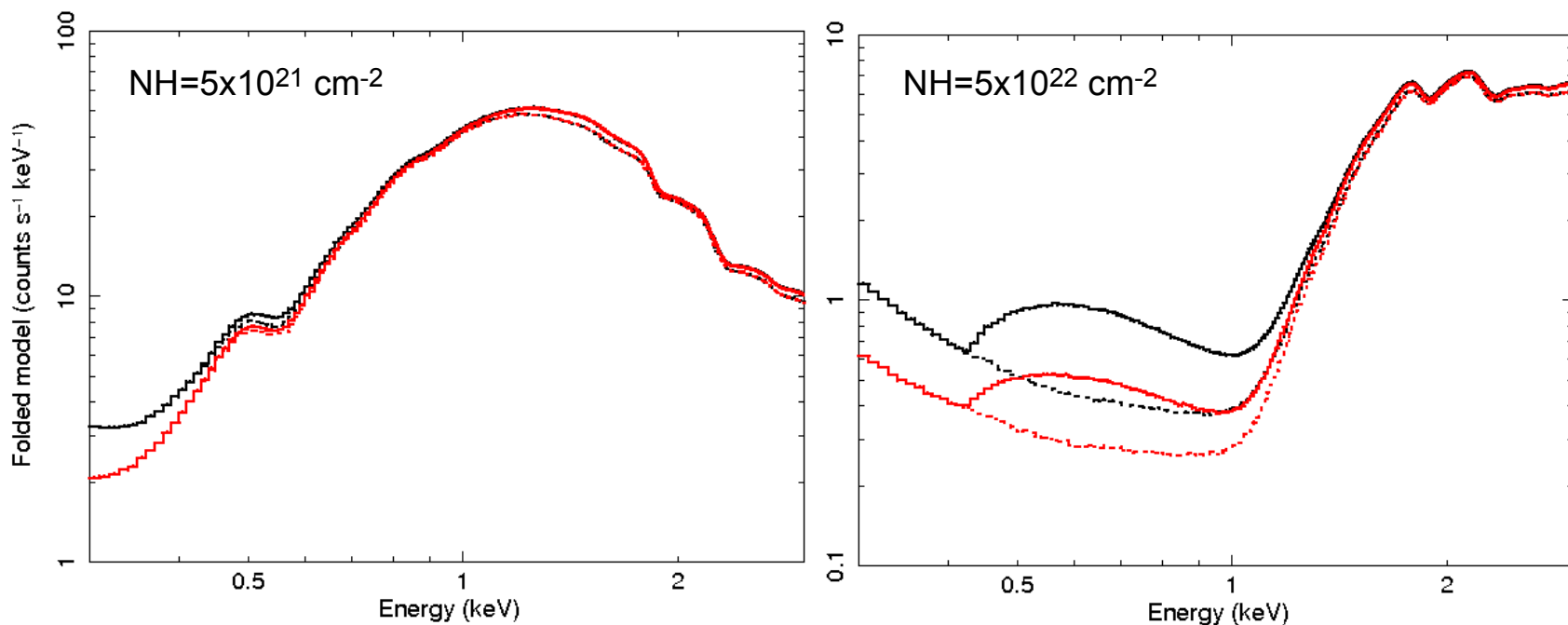


- Favourite combination has
 - RMF: $dd=22/35$ micron, $ff=48/35$ micron, $Na=2.5$, $s=1$, $Lf=250$ micron, $Ls=0.75$ micron
 - Mirror area: CH_2 thickness= 70 \AA , roughness= 4.5 \AA
 - Filter: Polyimide thickness= 2122 \AA , Al thickness= 473 \AA
- Became latest $V_{ss}=0V$ CALDB release (2013-Mar-15)

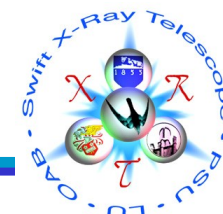


- Current WT RMFs generated assuming uniform illumination of the CCD
- Point source illumination can produce slightly different redistribution properties depending on the source position w.r.t. the 10-row binning boundaries
 - Source on the 10-row binning boundary suffers more event splitting (and more redistribution) than one 5 pixels away.
- NH dependent
 - kicks in when NH above a few $\times 10^{21}$ cm^{-2}





- Absorbed powerlaw ($\Gamma=2$) folded models
- Source at DETY=300.5 (black) and 305.5 (red)
- Grade 0-2 (solid), grade 0 (dashed)



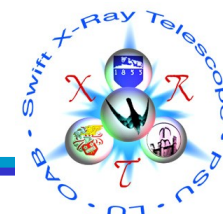
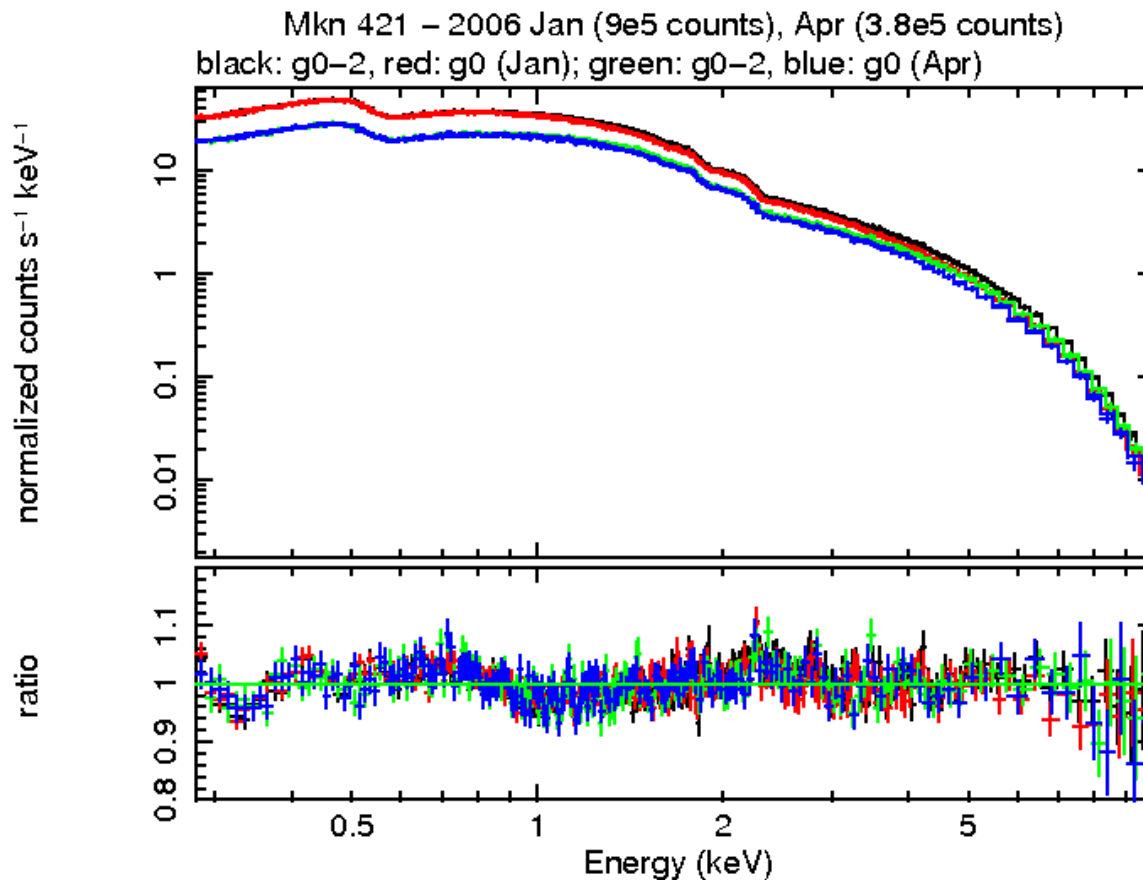
- After the substrate voltage change, expect a drop in QE at high E due to a reduction in depletion depth
 - confirmed with SNRG21.5 data
- Reduction in QE can be modelled by decreasing the depletion depth to ~ 20 micron.
 - However, this broadens the kernel (due to more field-free interactions) below Si edge \rightarrow slight higher NH for g0-12.



- Gain files updated 2013-Mar-15 (~6-12 monthly)
- New $V_{ss}=0V$ RMF/ARF released 2013-Mar-15
- New $V_{ss}=6V$ RMF/ARF needs further refinement and testing
 - Try and reduce the g0-12 redistribution shoulder below Si edge
 - Need to handle loss of QE at lowest E due to traps ?
- Expect WT redistribution to vary with point source location (DETY) on the CCD
 - Investigating how best to handle this



- 3-5% residuals with high S/N Mkn421 data



- RXJ1856: CF=1.07 WT (g0), 0.89 PC (g0)
- Clusters (PC):
 - kT~1-2 keV higher than PN/MOS (more in-line with Chandra ACIS). NH similar to CALDB
- Mkn421 (WT) : Gamma ~ 0.1 harder than MOS1, NH in agreement
- H1426 (PC) : slightly less curvature than MOS1; 0.1 harder than PN, NH in agreement
- 3c273 (WT) : Gamma, kT_{bb} in agreement with MOS1, Gamma ~0.05 harder than PN
- SNRG21.5 (PC) : made to agree with IACHEC average!

